



# Material Composition Declaration

## EPC2001C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	12.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	10.5319	84.33	86.48	843279
	Silicon oxide	7631-86-9	0.0406	0.32		3249
	Silicon nitride	12033-89-5	0.0126	0.10		1009
	Gallium nitride	25617-97-4	0.0494	0.40		3957
	Aluminum	7429-90-5	0.0835	0.67		6688
	Aluminum nitride	24304-00-5	0.0120	0.10		957
	Titanium	7440-32-6	0.0020	0.02		157
	Titanium nitride	25583-20-4	0.0071	0.06		571
	Copper	7440-50-8	0.0028	0.02		222
	Tungsten	7440-33-7	0.0022	0.02		180
	Polyimide		0.0570	0.46		4567
Under Bump Metal	Titanium	7440-32-6	0.0024	0.02	1.60	189
	Nickel	7440-02-0	0.0702	0.56		5617
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.1270	1.02		10170
Solder Bump	Tin	7440-31-5	1.4513	11.62	11.92	116208
	Silver	7440-22-4	0.0372	0.30		2980
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			12.5	100.00	100	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.